



Low Warp (~ 230 ° C)

【Conventional material】

Metal, other thermoplastic materials (PEEK, PES)

【Issues of conventional materials】

Metal: Metal dust (Impact on IC chips)

Polymer : Dimensional Stability as molded (warpage)

【Required characteristic】

Low warpage, antistatic ($10^6 \sim 10^{10} \Omega$)

AURUM™ Advantage

- Dimensional stability (low warp)
- Low dust emission

Maintain dimensional stability of molded parts at higher temperatures (warp)

☞ Recommended grade : JCF3025